

DOCKET NO: 251598US0



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

YUKIO HOSAKA, ET AL.

SERIAL NO: 10/820,123

FILED: APRIL 8, 2004

FOR: ABRASIVE PAD, METHOD AND
METAL MOLD FOR MANUFACTURING
THE SAME, AND SEMICONDUCTOR
WAFER POLISHING METHOD

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: EXAMINER: RACHUBA, MAURINA T.

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: GROUP ART UNIT: 3723

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AMENDMENT AND REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Official Action dated April 12, 2007, reconsideration is respectfully requested in the above-identified application in view of the following amendments and remarks:

Amendments to the Claims begin on page 2 of this response.

Support for the Amendments begin on page 7 of this response.

Remarks begin on page 8 of this response.

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DO NOT ENTER: /M.R./